

11-28-01

A

Atty. Dkt. No. 039153-0472 (G1177)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Besser et al.

Title: METHOD OF IMPLANTING  
COPPER BARRIER MATERIAL TO  
IMPROVE ELECTRICAL  
PERFORMANCE

Appl. No.: Unknown

Filing Date: Unknown

Examiner: Unknown

Art Unit: Unknown

CERTIFICATE OF EXPRESS MAILING	
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<i>Chris Escavaille</i>	
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UTILITY PATENT APPLICATION  
TRANSMITTAL

Assistant Commissioner for Patents  
Box PATENT APPLICATION  
2900 Crystal Drive  
Arlington, VA 22202-3513

Sir:

Transmitted herewith for filing under 37 C.F.R. § 1.53(b) is the nonprovisional utility patent application of:

Paul R. Besser  
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Sunnyvale, CA 94087

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[ ] Applicant claims small entity status under 37 CFR 1.27.

Enclosed are:

[ X ] Specification, Claim(s), and Abstract (14 pages).

11/26/01  
1054 U.S. PTO

1054 U.S. PTO  
09/994397  
11/26/01

09/994397 11/26/01

- ☒ Informal drawings (6 sheets, Figures 1-6).
- ☒ Declaration and Power of Attorney (6 pages).
- ☒ Assignment of the invention to Advanced Micro Devices, Inc..
- ☒ Assignment Recordation Cover Sheet.
- ☒ Check in the amount of \$40.00 for Assignment recordation.
- ☒ Request for application not to be published with certification under 35 USC 122(b)(2)(B)(i).
- ☒ Information Disclosure Statement.
- ☒ Form PTO-1449 with copies of 1 listed reference(s).

The filing fee is calculated below:

	Claims as Filed	Included in Basic Fee	Extra Claims	Rate	Fee Totals
Basic Fee				\$740.00	\$740.00
Total Claims:	20	20	0	x \$18.00	\$0.00
Independents:	3	3	0	x \$84.00	\$0.00
If any Multiple Dependent Claim(s) present:				+ \$280.00	\$0.00
				SUBTOTAL:	\$740.00
<input type="checkbox"/> Small Entity Fees Apply (subtract 1/2 of above):					\$0.00
				TOTAL FILING FEE:	\$740.00

- ☒ A check in the amount of \$740.00 to cover the filing fee is enclosed.
- ☐ The required filing fees are not enclosed but will be submitted in response to the Notice to File Missing Parts of Application.
- ☒ The Commissioner is hereby authorized to charge any additional fees which may be required regarding this application under 37 C.F.R. §§ 1.16-1.17, or credit any overpayment, to Deposit Account No. 06-1447. Should no proper payment be enclosed herewith, as by a check being in the wrong amount, unsigned, post-dated, otherwise improper or informal or even entirely missing, the Commissioner is authorized to charge the unpaid amount to Deposit Account No. 06-1447.

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Please direct all correspondence to the undersigned attorney or agent at the address indicated below.

Respectfully submitted,

Date Nov. 26, 2001

By



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<p>Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.</p>	
<p><b>REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b)(2)(B)(i)</b></p>	<p>First Named Inventor</p> <p>Paul R. Besser</p>
	<p>Title</p> <p>METHOD OF IMPLANTING COPPER BARRIER MATERIAL TO IMPROVE ELECTRICAL PERFORMANCE</p>
	<p>Atty Docket Number</p> <p>39153-472 (G1177)</p>

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

U.S.C. 122(b).  
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Nov. 26, 2001

Date \_\_\_\_\_

*Samuel Defuria*

**Signature**

Paul S. Hunter

Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

**Burden Hour Statement:** This collection of information is required by 37 CFR 1.213(a). The information is used by the public to request that an application not be published under 35 U.S.C. 122(b) (and the PTO to process that request). Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This form is estimated to take 6 minutes to complete. This time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. **DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.**